

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,953,375 B2
APPLICATION NO. : 10/813204
DATED : October 11, 2005
INVENTOR(S) : Kie Y. Ahn and Leonard Forbes

Page 1 of 2

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

<u>Column, Line</u>	<u>Reads</u>	<u>Should Read</u>
Item (56), Other Publications, Stevenson Reference	"of SiO ₂ , Films Over"	--of SiO ₂ Films Over--
Item (56), Other Publications, Vaudaine Reference	"technical digest of IEDM 91,"	--Technical Digest of IEDM 91,--
Column 4, Line 32	"FIG. 3), having a"	--FIG. 3) having a--
Column 5, Line 18	"ca. 10 ²⁻¹⁰³ "	--ca. 10 ² -10 ³ --
Column 6, Line 35	"Mater. Sci. 32, (1997),"	--Mater. Sci. 32 (1997),--
Column 7, Line 23	"69(7), (1996),"	--69(7) (1996)--
Column 7, Line 38	"Silicon at low"	--Silicon at Low--
Column 7, Line 53	"Part 1, Vol. 36,"	--Part I, Vol. 36,--
Column 9, Lines 24-25	"comprises chemical-mechanical polishing the porous"	--comprises chemical-mechanical polishing of the porous--
Column 10, Lines 26-27	"comprises chemical-mechanical polishing the porous"	--comprises chemical-mechanical polishing of the porous--
Column 10, Line 41	"act of fanning"	--act of forming--

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<u>Column, Line</u>	<u>Reads</u>	<u>Should Read</u>
Column 12, Lines 10-11	"comprises chemical-mechanical polishing the"	--comprises chemical-mechanical polishing of the--

Signed and Sealed this

Eighteenth Day of September, 2007



JON W. DUDAS
Director of the United States Patent and Trademark Office